



Final Product Change Notification

202104038F01 : NXP Final Test Site Relocation Initiative: ATTJ to ATTJ Building 2 (ATTJ-B2) - Phase 2 Qualification Results

Note: This notice is NXP Company Proprietary.

Issue Date: Apr 28, 2021 **Effective date:** May 28, 2021

Management summary

Due to the critical nature of semiconductor supply at this time, and capacity constraints at NXP ATTJ Tianjin, China, PCN 202104038F01 for Final Test Site Relocation ATTJ to ATTJ Building 2 (ATTJ-B2) requires an Effective Date of 30 days for supply assurance.

Change Category

- | | | | | |
|--|--|--|--|---|
| <input type="checkbox"/> Wafer Fab Process | <input type="checkbox"/> Assembly Process | <input type="checkbox"/> Product Marking | <input type="checkbox"/> Test Process | <input type="checkbox"/> Design |
| <input type="checkbox"/> Wafer Fab Materials | <input type="checkbox"/> Assembly Materials | <input type="checkbox"/> Mechanical Specification | <input type="checkbox"/> Test Equipment | <input type="checkbox"/> Errata |
| <input type="checkbox"/> Wafer Fab Location | <input type="checkbox"/> Assembly Location | <input type="checkbox"/> Packing/Shipping/Labeling | <input checked="" type="checkbox"/> Test Location | <input type="checkbox"/> Electrical spec./Test coverage |
| <input type="checkbox"/> Firmware | <input type="checkbox"/> Other | | | |

PCN Overview

Description

NXP Semiconductors announces the ATTJ Final Test Site Relocation Qualification Results from the current NXP ATTJ, Tianjin, China test site to local, nearby (2.5km away) ATTJ-B2 test site, creating a consolidated ATTJ Test Center of Excellence. The associated Test Backend Shipping / Packing Operations relocate to the ATTJ-B2 site as well.

This NXP Initiative is a phased / ramped relocation activity, until all Final Test platform types have been relocated to the ATTJ-B2.

This major, strategic NXP initiative ensures future scalability of NXP ATTJ backend manufacturing sites, ATTJ main factory and new ATTJ-B2, to support current and future business. The current ATTJ main factory manufacturing floor space is fully utilized. Final Test and Test Backend Shipping / Packing Operations must be migrated to the new ATTJ-B2 Test Center of Excellence, while the existing ATTJ main factory will be exclusive for assembly and other non-Final Test operations. This initiative allows growth opportunities for both ATTJ manufacturing buildings for customer supply assurance.

The ATTJ-B2 is located 2.5 km Southeast from the current ATTJ main factory site, and adheres to the same ATTJ criteria: 100k clean room rating, temperature / humidity / ESD controls, and quality accreditations.

All current ATTJ main factory Final Test equipment (hardware / software), test flows, test programs, policies, procedures, and personnel will be relocated to the new ATTJ-B2. Absolutely no impact to product form, fit, function or reliability.

Please see the attached documents for additional details, including Qualification Results.

Corresponding ZVEI Delta Qualification Matrix ID: SEM-TF-01

Reason

Qualification of NXP ATTJ, Tianjin, China new ATTJ-B2 Final Test site is critical for product supply assurance due to the global semiconductor supply and capacity constraints, including current NXP ATTJ Tianjin, China Final Test Site.

Identification of Affected Products

Product identification does not change

Product Availability

Sample Information

Not Applicable

Production

Planned first shipment May 28, 2021

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No Impact on form, fit, function, reliability or quality

Disposition of Old Products

Existing inventory will be shipped until depleted

Additional information

Self qualification: [view online](#)

Additional documents: [view online](#)

Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by May 28, 2021.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

| | |
|---------------------------|---------------------------------------|
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At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards. Customer Focus, Passion to Win.

NXP Quality Management Team.

About NXP Semiconductors

NXP Semiconductors N.V. (NASDAQ: NXPI) provides High Performance Mixed Signal and Standard Product solutions that leverage its leading RF, Analog, Power Management, Interface, Security and Digital Processing expertise. These innovations are used in a wide range of automotive, identification, wireless infrastructure, lighting, industrial, mobile, consumer and computing applications.

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